



Product Change Notification

Change Notification #: 116519 - 00
Change Title: Select Intel® SSD DC 3100p Series,
PCN 116519-00,
Product Discontinuance,
End of Life
Date of Publication: October 09, 2018

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Last Product Discontinuance Order Date:	February 5, 2019
Last Product Discontinuance Shipment Date:	June 5, 2019

Description of Change to the Customer:

Intel is announcing the End of Life timeline for the Intel® SSD DC 3100p Series SKUs.

These products, listed on the "Products Affected/Intel Ordering Codes" table below, will be discontinued and unavailable for additional orders after the February 5, 2019.

Effective June 5, 2019, Intel will stop shipping Intel® SSD DC 3100p Series SKUs.

Customer Impact of Change and Recommended Action:

While Intel will make commercially reasonable efforts to support last time order quantities, it is recommended for customers to transition to the next generation of products.

Please contact your local Intel Field Sales representative if you have any further questions about this End of Life notice.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD DC P3100 Series (128GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA128G701	953765
Intel® SSD DC P3100 Series (256GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA256G701	953766
Intel® SSD DC P3100 Series (512GB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA512G701	953767
Intel® SSD DC P3100 Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D1, TLC) Generic Single Pack	SSDPEKKA010T701	953769

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 9, 2018	00	Originally Published PCN



Product Change Notification

116519 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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